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FOR IMMEDIATE RELEASE

Press Release

YINCAE's DA158N Die Attach Materials withstanding -273°C

(Albany, NY) 03/30/2022 — YINCAE is excited to announce that we have developed DA158N die attach materials which are thermal conductive and electrical insulating adhesives. It can be quickly cured at low temperatures. The development of DA 158N is preparing the materials for people to live on Mars.

Due to its unique properties, DA158N die attach adhesive has a high thermal conductivity and can achieve very thin bonding line thickness, there is no bleeding and migration issue. Furthermore, the DA 158N has excellent bonding strength, and a thermal cycling performance that is significantly greater than that of the leading competitors'. The DA 158N can withstand extreme temperatures (-273°C) without any delamination, and still outperform current competitor products on the market. This not only has extraordinary implications for the use of DA 158N but also indicates the broad range of uses it potentially has across current industries.

This material can be used for all die attach applications, particularly for harsh condition application. While it is also suitable for bare chip protection in a variety of advanced packages such as memory cards, chip carriers, hybrid circuits and multi-chip modules.

It is designed for high production and friendly environments where process speed and reliability are the key concerns. This material is easily dispensed, minimizes induced stresses, provides outstanding reliability performance (e.g. temperature cycling performance), and excellent mechanical resistance.

For more information on YINCAE's SMT DA 158N, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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